

What Is Claimed Is:

1. A capacitive micromechanical pressure sensor comprising:
  - a first component including a first electrode, the first component including a semiconductor material; and
  - a second component including a first diaphragm, the second component being at least partially composed of metal,wherein a capacitance is measured via at least the first electrode and a movement of the first diaphragm, and
  - wherein the first and second components are processed separately.
2. The pressure sensor according to claim 1, wherein one of the first component and the second component includes a second electrode, the capacitance being measured via the second electrode.
3. The pressure sensor according to claim 2, wherein the second electrode is in the second component and is implemented by the first diaphragm.
4. The pressure sensor according to claim 1, wherein the second component has a steel diaphragm.
5. The pressure sensor according to claim 1, wherein the first component has at least a part of a circuit for analyzing a capacitance measurement, the circuit being situated on a side of the first component opposite the first electrode, the first electrode being contacted with the circuit via an electric connection within the components.
6. The pressure sensor according to claim 1, further comprising a non-conductive material connecting the first and second components to one another.
7. The pressure sensor according to claim 2, wherein the second electrode is moveable with respect to the first electrode in such a way that a movement of the second electrode takes place as a function of a movement of the first diaphragm, a

distance between the first and second electrodes changing linearly with the movement of the first diaphragm.

8. A method for manufacturing a capacitive micromechanical pressure sensor, the method comprising:

providing a first component including a first electrode, the first component including a semiconductor material; and

providing a second component including a first diaphragm, the second component being at least partially composed of metal,

wherein a capacitance is measured via at least the first electrode and the first diaphragm,

wherein the first and second components are processed differently, and

wherein the pressure sensor is manufactured by assembling the first and second components.

9. The method according to claim 8, further comprising producing a second electrode in one of the first component and the second component.

10. The method according to claim 9, wherein the second electrode in the second component is implemented by the first diaphragm.

11. The method according to claim 8, further comprising producing at least a part of a circuit for analyzing a capacitance measurement one of in and on the first component.

12. The method according to claim 11, wherein the circuit is produced on a side of the first component opposite the first electrode, and wherein the first electrode is contacted with the circuit via an electric connection within the components.

13. The method according to claim 8, wherein the first and second components are connected to one another by a non-conductive material.

14. The method according to claim 9, wherein the second electrode in the first component is movable with respect to the first electrode in such a way that a movement of the second electrode takes place as a function of a movement of the first diaphragm, a distance between the first and second electrodes changing linearly with the movement of the first diaphragm.